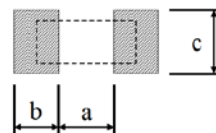
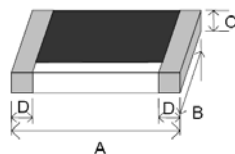


A. Electrical Specifications:

Part No.	L (nH)	Tolerance	Q Min.	SRF Min. (GHz)	DCR Max. (Ω)	I DC Max. (mA)
0201TF-N10_	0.1	B, C, S	8/500MHz	9	0.20	400
0201TF-N20_	0.2	B, C, S	8/500MHz	9	0.20	400
0201TF-N30_	0.3	B, C, S	8/500MHz	9	0.20	400
0201TF-N40_	0.4	B, C, S	8/500MHz	9	0.25	350
0201TF-N50_	0.5	B, C, S	8/500MHz	9	0.25	350
0201TF-N60_	0.6	B, C, S	8/500MHz	9	0.25	350
0201TF-N70_	0.7	B, C, S	8/500MHz	9	0.30	300
0201TF-N80_	0.8	B, C, S	8/500MHz	9	0.30	300
0201TF-N90_	0.9	B, C, S	8/500MHz	9	0.30	300
0201TF-1N0_	1.0	B, C, S	8/500MHz	9	0.30	300
0201TF-1N1_	1.1	B, C, S	8/500MHz	9	0.35	300
0201TF-1N2_	1.2	B, C, S	8/500MHz	9	0.35	300
0201TF-1N3_	1.3	B, C, S	8/500MHz	9	0.45	250
0201TF-1N4_	1.4	B, C, S	8/500MHz	9	0.45	250
0201TF-1N5_	1.5	B, C, S	8/500MHz	9	0.45	250
0201TF-1N6_	1.6	B, C, S	8/500MHz	9	0.55	200
0201TF-1N7_	1.7	B, C, S	8/500MHz	9	0.55	200
0201TF-1N8_	1.8	B, C, S	8/500MHz	9	0.55	200
0201TF-1N9_	1.9	B, C, S	8/500MHz	9	0.55	200
0201TF-2N0_	2.0	B, C, S	8/500MHz	8	0.70	200
0201TF-2N1_	2.1	B, C, S	8/500MHz	8	0.70	200
0201TF-2N2_	2.2	B, C, S	8/500MHz	8	0.70	200
0201TF-2N3_	2.3	B, C, S	8/500MHz	8	0.80	150
0201TF-2N4_	2.4	B, C, S	8/500MHz	8	0.80	150
0201TF-2N5_	2.5	B, C, S	8/500MHz	8	0.80	150
0201TF-2N6_	2.6	B, C, S	8/500MHz	8	0.80	150
0201TF-2N7_	2.7	B, C, S	8/500MHz	8	0.80	150
0201TF-2N8_	2.8	B, C, S	8/500MHz	6	1.00	150
0201TF-2N9_	2.9	B, C, S	8/500MHz	6	1.00	150
0201TF-3N0_	3.0	B, C, S	8/500MHz	6	1.00	150
0201TF-3N1_	3.1	B, C, S	8/500MHz	6	1.00	150
0201TF-3N2_	3.2	B, C, S	8/500MHz	6	1.00	150
0201TF-3N3_	3.3	B, C, S	8/500MHz	6	1.00	150
0201TF-3N4_	3.4	B, C, S	8/500MHz	6	1.20	150
0201TF-3N5_	3.5	B, C, S	8/500MHz	6	1.20	150
0201TF-3N6_	3.6	B, C, S	8/500MHz	6	1.20	150
0201TF-3N7_	3.7	B, C, S	8/500MHz	6	1.20	150
0201TF-3N8_	3.8	B, C, S	8/500MHz	6	1.20	150
0201TF-3N9_	3.9	B, C, S	8/500MHz	6	1.20	150
0201TF-4N0_	4.0	B, C, S	8/500MHz	6	1.20	150
0201TF-4N4_	4.4	B, C, S	8/500MHz	6	1.30	140
0201TF-4N7_	4.7	B, C, S	8/500MHz	6	1.40	130
0201TF-4N9_	4.9	B, C, S	8/500MHz	6	1.60	130
0201TF-5N6_	5.6	G, J	8/500MHz	4	1.80	130
0201TF-6N1_	6.1	G, J	8/500MHz	4	2.00	120
0201TF-6N8_	6.8	G, J	8/500MHz	4	2.30	110
0201TF-7N4_	7.4	G, J	8/500MHz	4	2.80	110
0201TF-8N2_	8.2	G, J	8/500MHz	3	3.00	110
0201TF-9N1_	9.1	G, J	8/500MHz	3	3.25	100
0201TF-9N2_	9.2	G, J	8/500MHz	3	3.25	100
0201TF-10N_	10.0	G, J	8/500MHz	2	3.50	80

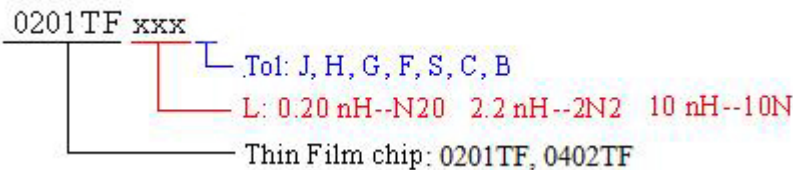
B. Dimensions and Recommend Land Pattern: (mm/Inch)

Series	A	B	C	D	a	b	c
0201TF	0.60±0.05 (0.024±0.002)	0.30±0.05 (0.012±0.002)	0.23±0.05 (0.009±0.002)	0.15±0.05 (0.006±0.002)	0.30 (0.0118)	0.25 (0.010)	0.30±0.20 (0.0118±0.008)



Recommend Land Pattern

C. Part Number (Example):



D. General information:

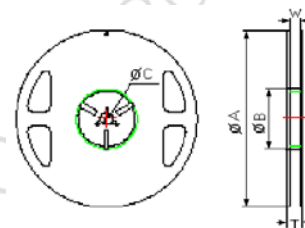
1. 0201TF-xxx, "0201TF" = P/N, "xxx" = Inductance, "-" = Tolerance.
2. Tolerance "-": J: $\pm 5\%$, H: $\pm 3\%$, G: $\pm 2\%$, F: $\pm 1\%$, B: $\pm 0.1\text{nH}$, C: $\pm 0.2\text{nH}$, S: $\pm 0.3\text{nH}$.
3. A Photo Lithographic Single Layer Ceramic Chip.
4. High SRF, Excellent Q, Superior Temperature Stability
5. Tight Tolerance of $\pm 1\%$ or $\pm 0.1\text{nH}$
6. Stable Inductance in High Frequency Circuit
7. Maximum Temperature Rise: 15°C (when measured at 25°C ambient).
8. Inductance & Q measured using the HP4286A and Agilent 16196B.
9. SRF measured using the HP8720D or HP8753E.
10. DCR measured using the 502BC.
11. Operating temperature: -40°C to $+125^\circ\text{C}$.
12. Storage Temperature: $25^\circ\text{C} \pm 3^\circ\text{C}$; Humidity < 80%RH
13. Inductance Range: 0.10 nH (400 mA) ~ 10.0 nH (80 mA), SRF from 9.0 GHz to 2.0 GHz.
14. MSL: Level 1.

E. Applications:

1. Cellular-phone, Pagers and GPS Products.
2. VCO, TCXO Circuit and RF Transceiver Module.
3. Wireless LAN, Bluetooth Module, Communication Appliances Hybrid.

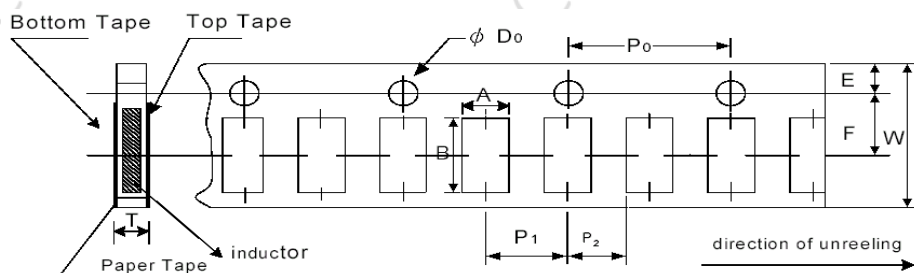
F. Reel Specification:

Series	ϕA	ϕB	ϕC	W	T	Quantity
0201TF	178 ± 1 (7 ± 0.040)	60 ± 1.0 (0.236 ± 0.040)	13.5 ± 0.70 (0.531 ± 0.028)	9.5 ± 1.0 (0.374 ± 0.040)	11.5 ± 1.0 (0.453 ± 0.040)	10,000 PCS



G. Paper Tape Specification:

Series	A	B	W	E	F	Po	P1	P2	ϕDo	T
0201TF	0.40 ± 0.05 (0.016 ± 0.002)	0.70 ± 0.05 (0.028 ± 0.002)	8.00 ± 0.10 (0.315 ± 0.004)	1.75 ± 0.05 (0.069 ± 0.002)	3.50 ± 0.05 (0.138 ± 0.002)	4.00 ± 0.10 (0.158 ± 0.004)	2.00 ± 0.05 (0.079 ± 0.002)	2.00 ± 0.05 (0.079 ± 0.002)	1.55 ± 0.05 (0.061 ± 0.002)	0.42 ± 0.02 (0.017 ± 0.0008)



Tape & Reel Storage Temperature: $25^\circ\text{C} \pm 3^\circ\text{C}$, Humidity: < 80% RH.

H. Environmental Characteristics:

ITEM	Specification	Test Method
1 Inductance	As SPEC.	Measuring equipment and fixture: HP4287 + Agilent 16196C
2 Insulation Resistance	$>1000M\Omega$	MIL-STD-202F Method 302 Apply $100V_{\infty}$ for 1 minute
3 Damp Heat with Load	$\Delta L \leq 10\%$	MIL-STD-202F Method 103B $40 \pm 2^{\circ}C$, 90~95% R.H. Max. working voltage for 1000 hrs with 1.5 hrs "ON" and 0.5 hrs "OFF"
4 Bending Strength	As SPEC.	JIS-C-5201-1 6.1.4 Bending Amplitude 3mm for 10 seconds
5 Solder-ability	95% min coverage	MIL-STD-202F Method 208H $245 \pm 5^{\circ}C$ for 3 seconds
6 Resistance to Soldering Heat	$\Delta L \leq 10\%$	MIL-STD-202F Method 210E $260 \pm 5^{\circ}C$ for 10 seconds
7 Dielectric Withstand Voltage	$>100V$	MIL-STD-202F Method 301. Apply 100VA (rms) for 1minute.
8 High Temperature Exposure	$\Delta L \leq 10\%$	JIS-C-5201-1-7.2 $85^{\circ}C \pm 2^{\circ}C$, 1000 +48/-0 hours
9 Low Temperature Storage	$\Delta L \leq 10\%$	JIS-C-5201-1-7.1 $-40^{\circ}C \pm 3^{\circ}C$, 1000 +48/-0 hours
10 Temperature Cycle	$\Delta L \leq 10\%$	JIS-C-5201-1-7.4 -40/RT/85/RT, 10 cycles

- Storage Temperature: $25 \pm 3^{\circ}C$; Humidity $< 80\% RH$

J. Solder Profile:

